

Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	5 X 4 X 0.75 (3.6 X 2.6 EP)
Lead Count	18
Terminal Finish	100 Sn
MS Number	MS011003C

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	1.97E-02	86.91	869100	36.64		366443
Thermosets	Epoxy & Phenol Resin	Proprietary	2.90E-03	12.78	127800	5.39		53885
Other inorganic materials	Carbon black	1333-86-4	7.03E-05	0.31	3100	0.13		1307
Subtotal			2.27 E-02	100.00	1000000	42.16		421635

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	2.25 E-02	97.50	975000	41.87		418749
Copper & its alloys	Iron	7439-89-6	5.43 E-04	2.35	23500	1.01		10093
Copper & its alloys	Zinc	7440-66-6	2.77 E-05	0.12	1200	0.05		515
Copper & its alloys	Phosphorus	7723-14-0	6.93 E-06	0.03	300	0.01		129
Subtotal			2.31 E-02	100.00	1000000	42.95		429486

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	5.56 E-04	100.0	1000000	1.03		10340

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	1.16 E-03	100.0	1000000	2.16		21637

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	8.26 E-04	99.0	990000	1.54		15355
Precious metals	Palladium	7440-05-3	8.34 E-06	1.0	10000	0.016		155
Subtotal			8.34 E-04	100.0	1000000	1.55		15510

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	4.60 E-03	100.0	1000000	8.56		85591

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	6.25 E-04	73.54	735400	1.16		11620
Other organic materials	Epoxy resin A	TS ref# 10013	6.25 E-05	7.35	73500	0.12		1161
Others	Anhydride	TS ref# 10181	6.25 E-05	7.35	73500	0.12		1161
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	2.50 E-05	2.94	29400	0.05		465
Other organic materials	Epoxy resin B	TS ref# 10237	2.50 E-05	2.94	29400	0.05		465
Others	Epoxy resin modifier	TS ref# 10038	2.50 E-05	2.94	29400	0.05		465
Others	Anhydride	TS ref# 10180	2.50 E-05	2.94	29400	0.05		465
Subtotal			8.50 E-04	100.0	1000000	1.58		15801

Package Totals			Weight (g) 5.38 E-02			Percentage (%) 100		PPM 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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